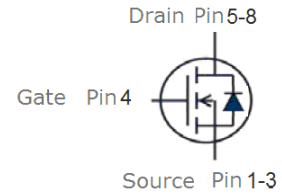
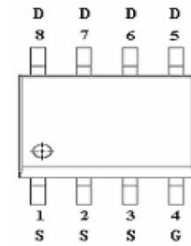


**Features**

- Low Input Capacitance
- Low Miller Charge
- Low on-resistance $R_{DS(on)}$ @ $V_{GS}=4.5\text{ V}$
- Low Input/Output Leakage
- Pb-free lead plating; RoHS compliant

V_{DS}	65	V
$R_{DS(on), Typ} @ V_{GS}=10\text{ V}$	7.0	m Ω
I_D	80	A

**Simplified Outline****Application**

- Motor / Body Load Control

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter			Value	Unit
Drain-Source Voltage		V_{DS}	65	V
Gate-Source Voltage		V_{GS}	± 20	V
Drain Current-Continuous	$T_A=25^\circ\text{C}$	I_D	80	A
	$T_A=70^\circ\text{C}$		40	A
Drain Current-Pulsed ^{Note 1}		I_{DM}	320	A
Maximum Power Dissipation	$T_A=25^\circ\text{C}$	P_D	2.5	W
	$T_A=70^\circ\text{C}$		2.0	W
Storage Temperature Range		T_{STG}	-55 to +150	$^\circ\text{C}$
Operating Junction Temperature Range		T_J	-55 to +150	$^\circ\text{C}$

Thermal Resistance Ratings

Parameter		Conditions	Min.	Typ.	Max.	Unit
Maximum Junction-to-Ambient	$R_{\theta JA}$	Steady State	-	-	75	$^\circ\text{C/W}$
Maximum Junction-to-Ambient	$R_{\theta JA}$	$t \leq 10\text{ s}$	-	-	40	$^\circ\text{C/W}$
Maximum Junction-to-Case	$R_{\theta JC}$	Steady State	-	-	24	$^\circ\text{C/W}$

Electrical Characteristics (T_J = 25°C unless otherwise noted)

OFF CHARACTERISTICS						
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_{DS} = 250\mu A$	65	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 48V, V_{GS} = 0V$	-	-	1	μA
Gate-Body Leakage	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	± 100	nA

ON CHARACTERISTICS						
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS} = V_{GS}, I_{DS} = 250\mu A$	1.2	1.7	2.5	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS} = 10V, I_{DS} = 12A$	-	-	7.5	m Ω
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS} = 4.5V, I_{DS} = 9A$	-	-	9	m Ω
Forward Transconductance	g_{fs}	$V_{DD} = 10V, I_{DD} = 6A$	-	11	-	S

DYNAMIC CHARACTERISTICS						
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Input Capacitance	C_{iss}	$V_{DS} = 30V, V_{GS} = 0V, f = 1MHz$	-	3450	-	pF
Output Capacitance	C_{oss}		-	310	-	
Reverse Transfer Capacitance	C_{rss}		-	115	-	

SWITCHING CHARACTERISTICS						
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Turn-On Delay Time	$T_{d(on)}$	$V_{GS} = 10V, V_{DS} = 30V, R_L = 5\Omega, R_{GEN} = 3\Omega$	-	28	-	ns
Rise Time	t_r		-	32	-	
Turn-Off Delay Time	$T_{d(off)}$		-	98	-	
Fall Time	t_f		-	68	-	
Total Gate Charge	Q_g	$V_{GS} = 10V, V_{DS} = 30V, I_D = 10A$	-	75	-	nC
Gate to Source Gate Charge	Q_{gs}		-	19	-	
Gate to Drain "Miller" Charge	Q_{gd}		-	26	-	
Gate resistance	R_g	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$	-	1.2	-	Ω

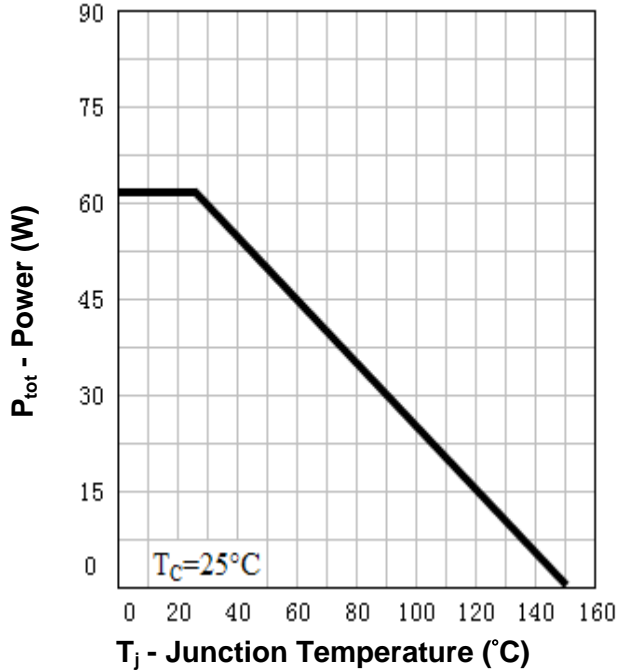
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS} = 0V, I_S = 1A$	-	-	1.3	V
Continuous Source Current	I_S	$I_F = 12A, di/dt = 500A/\mu s$	-	13	-	A
Pulsed Source Current	I_{SM}		-	45	-	A

- Notes:**
- Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
 - $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design. $R_{\theta JA}$ shown below for single device operation on FR-4 in still air.

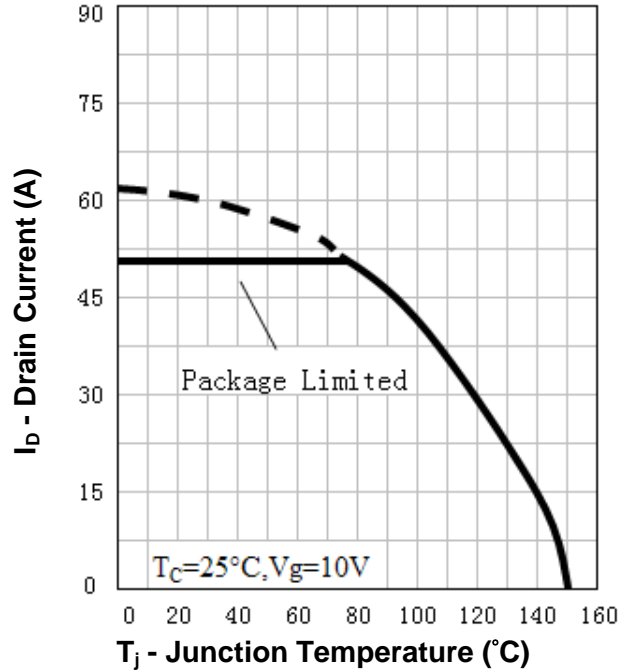


Typical Characteristics

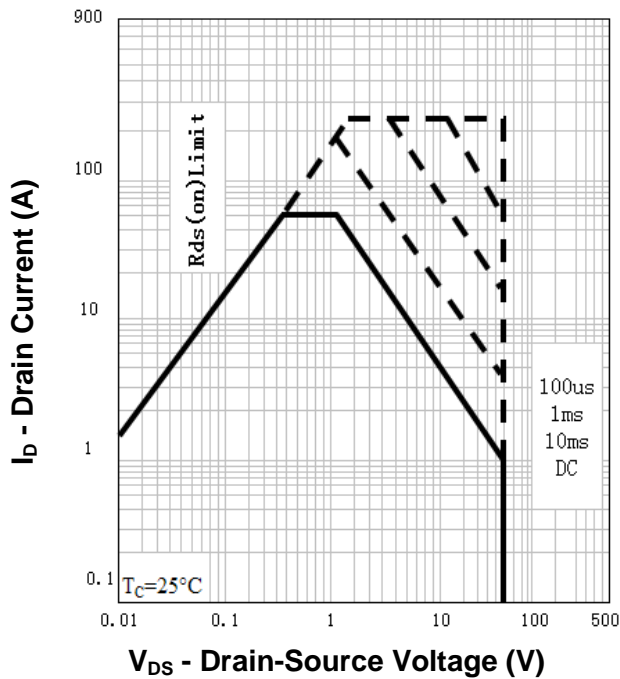
Power Dissipation



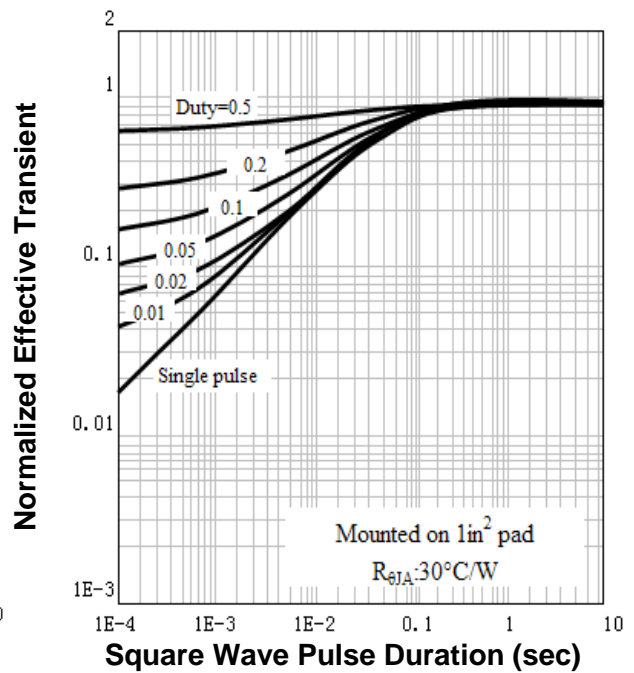
Drain Current



Safe Operation Area

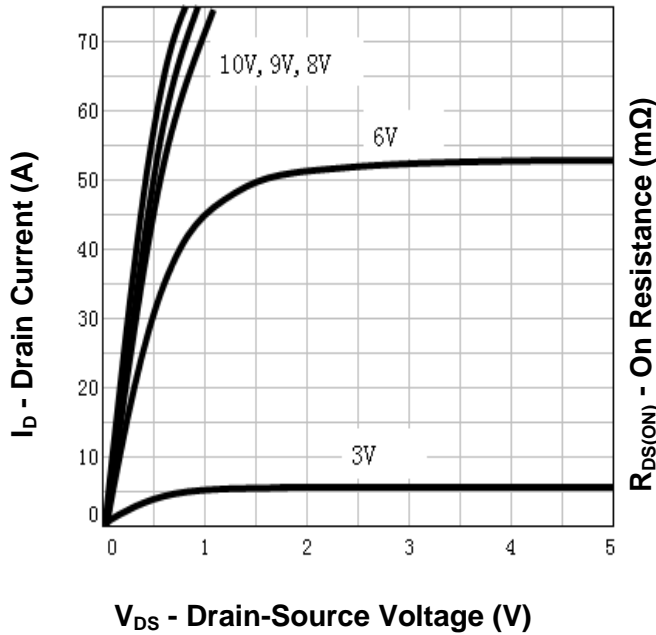


Thermal Transient Impedance

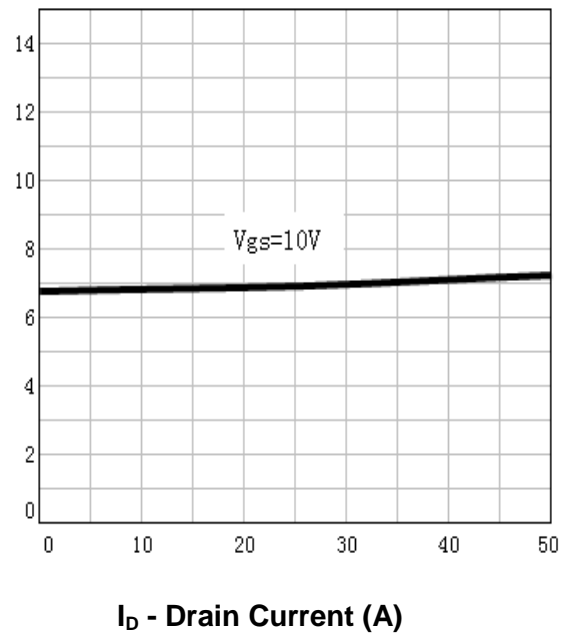


Typical Characteristics

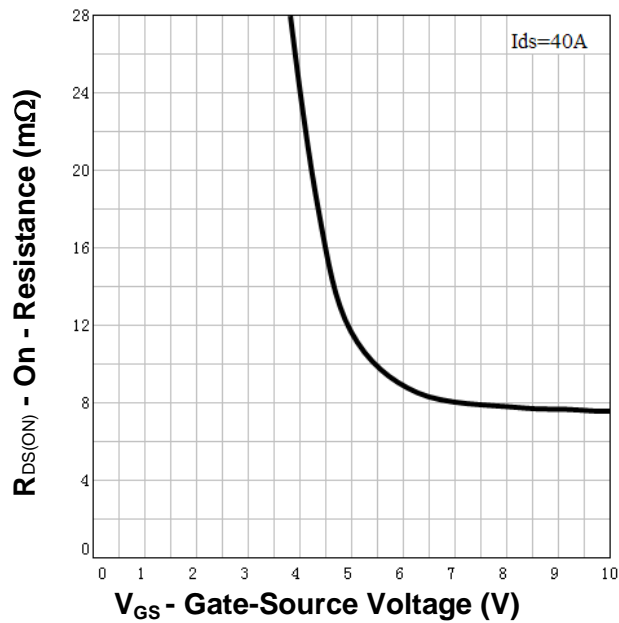
Output Characteristics



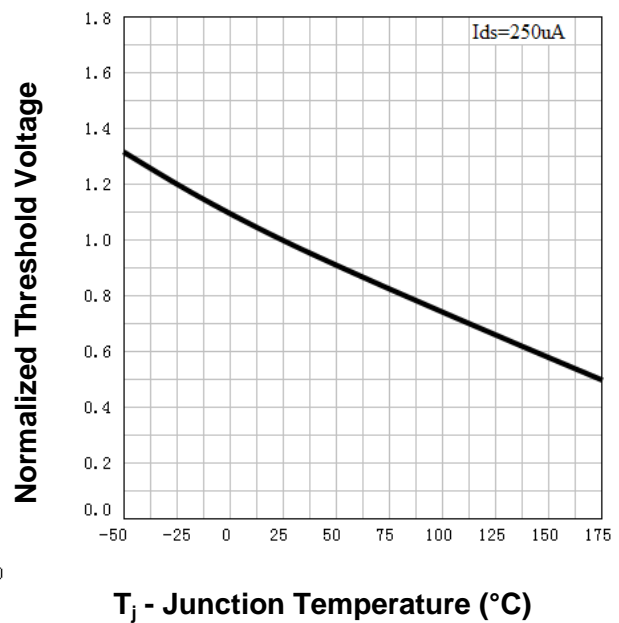
Drain-Source On Resistance



Drain-Source On Resistance



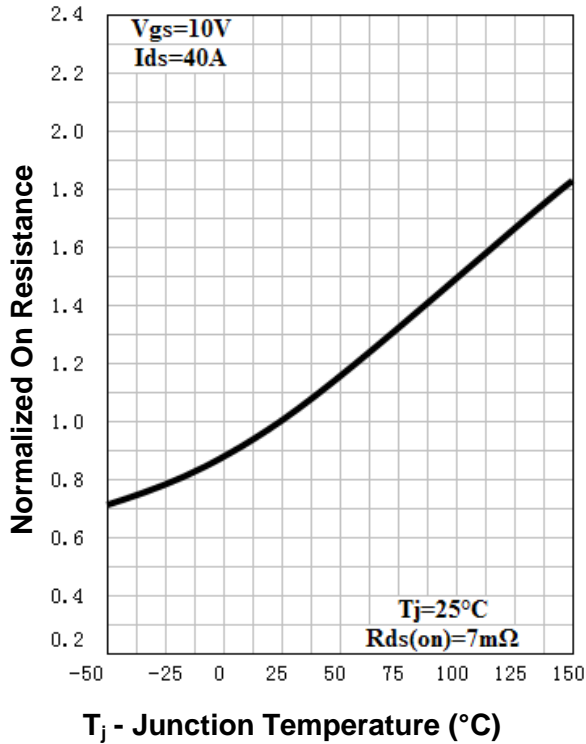
Gate Threshold Voltage



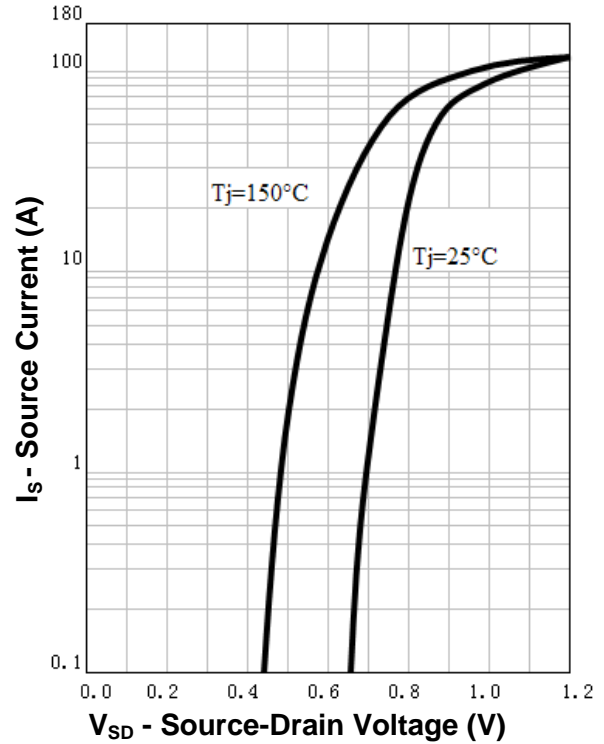


Typical Characteristics

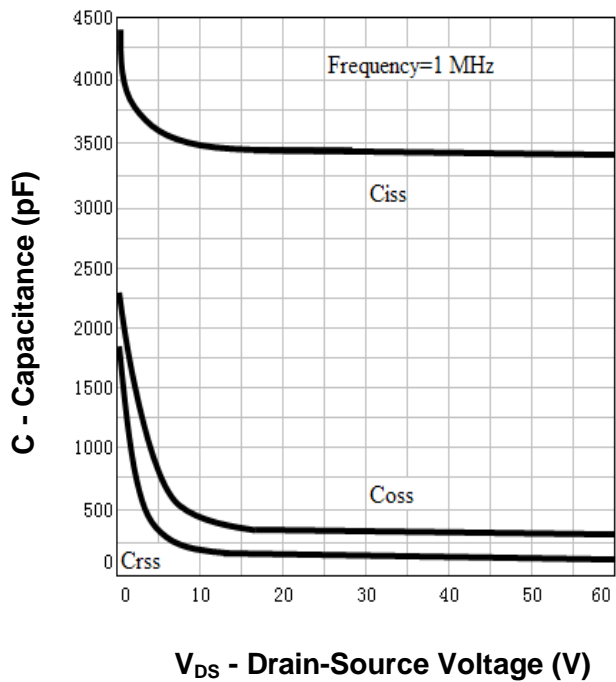
Drain-Source On Resistance



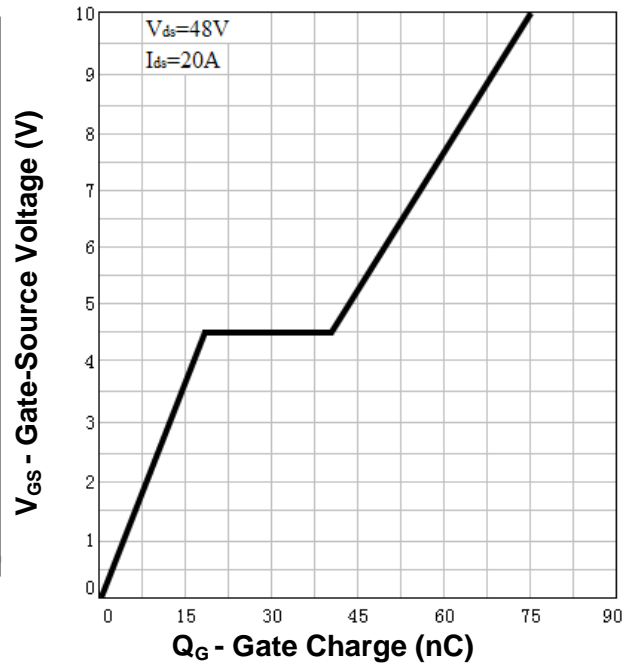
Source-Drain Diode Forward



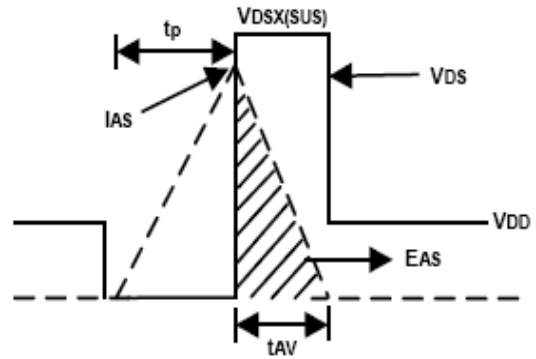
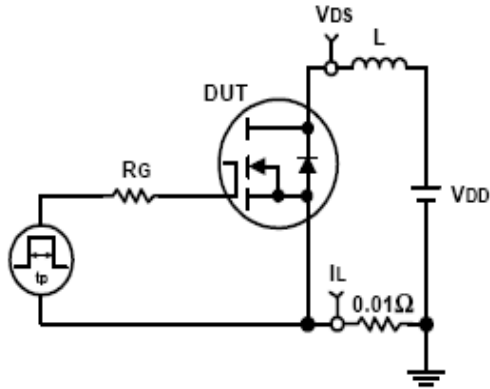
Capacitance



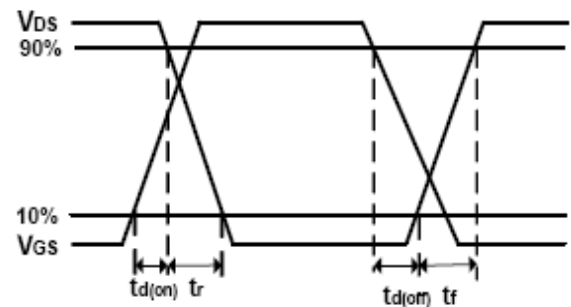
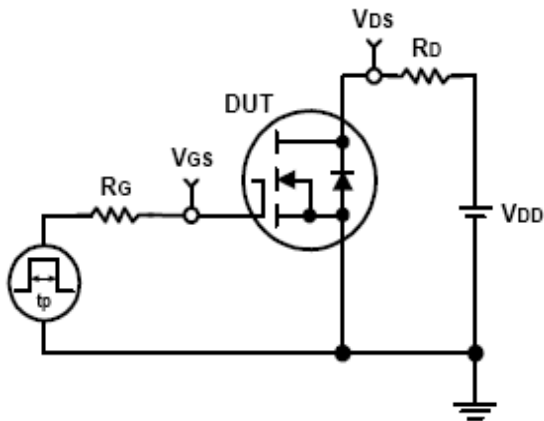
Gate Charge



Avalanche Test Circuit and Waveforms

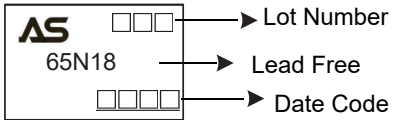
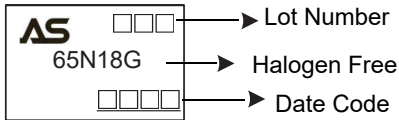


Switching Time Test Circuit and Waveforms

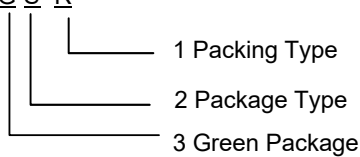


Ordering and Marking Information

Device	Marking	Package	Packing	Quantity
ASDM65N18S	65N18	SOP-8	Tape&Reel	4000

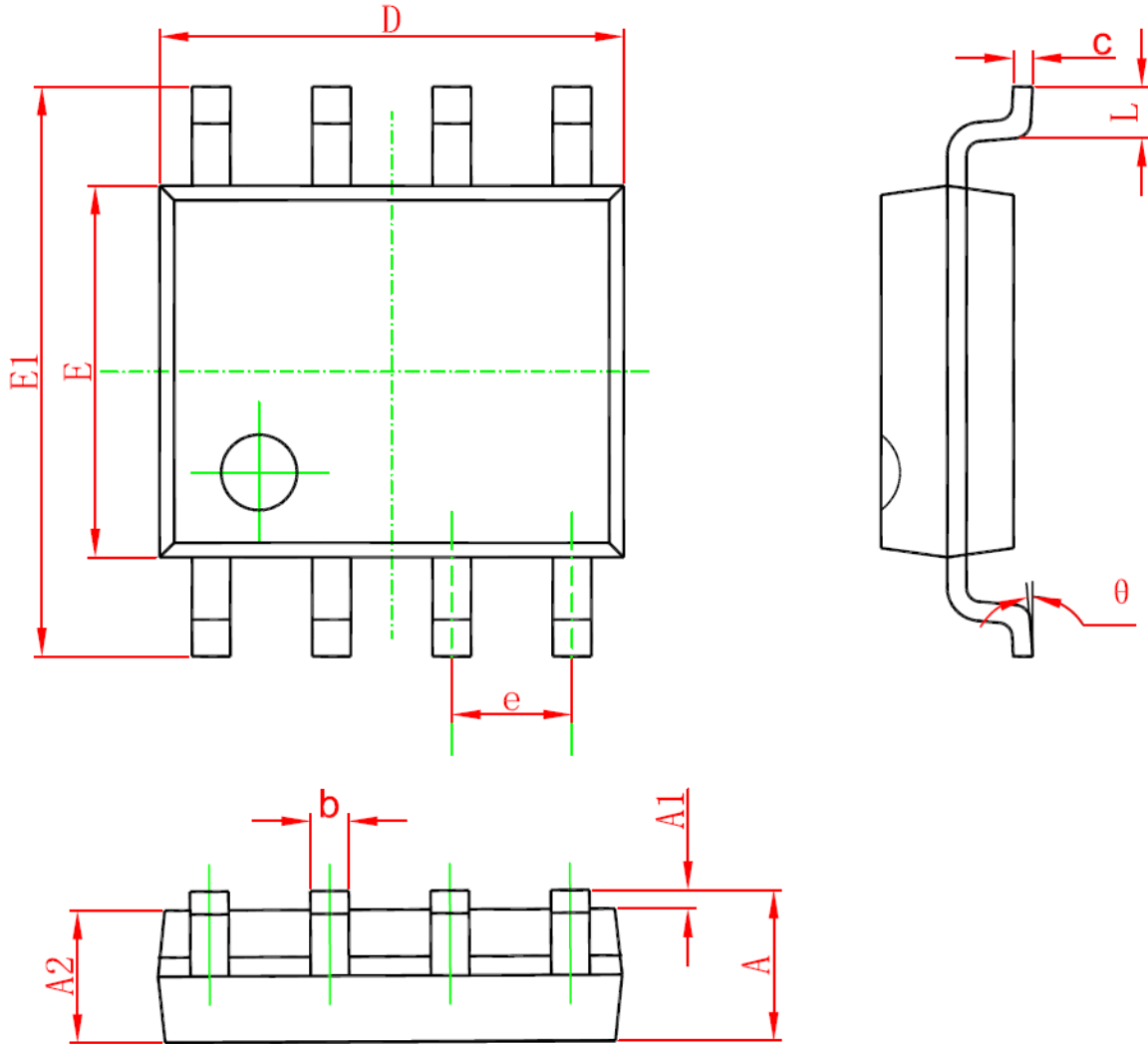
PACKAGE	MARKING
SOP-8	 

Ordering Number		Package
Lead Free	Halogen Free	
ASDM65N18-S-R	ASDM65N18G-S-R	SOP-8

<p>ASDM65N18G-S-R</p> 	<p>1 R:Tape Reel</p> <p>2 S:SOP-8</p> <p>3 blank: Lead Free</p> <p>G:Halogen Free</p>
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SOP-8 PACKAGE IN FORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

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